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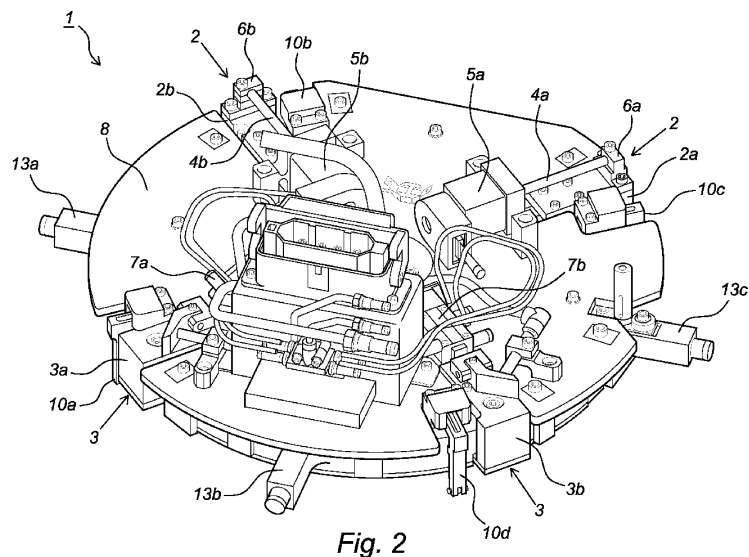


Fig. 2

(57) **Abstract:** The present invention relates to a handler device for handling substrates during semiconductor production, comprising a handling unit having a substrate facing side to be directed to the substrate to be handled, said handling unit being provided with at least three substrate edge grippers protruding from the substrate facing side of the handling unit. The substrate edge grippers are configured to grip the edge of a substrate to be handled, wherein the at least three substrate edge grippers comprise: at least two controlled moveable positioning grippers for gripping the edge of the substrate at two controlled positions and at least one clamping gripper for exerting a controlled clamping force onto the edge of the substrate at least partially directed towards the positioning grippers. The handler further comprises individually controllable actuators connected to the handling unit for independent control of each of the controlled moveable positioning grippers.

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